[METHOD FOR IMPROVING RELIABILITY OF STI]

Abstract of Disclosure

An improved STI method having an ISSG film as an interface reinforcement layer is disclosed. The present invention includes the following steps of forming a trench—patterned mask layer on the top surface of a substrate exposing an unmasked trench region of the substrate. The mask layer is a pad oxide layer and a silicon nitride layer formed on the pad oxide layer. The unmasked region of the substrate is etched to form a trench on the substrate and the silicon nitride layer and the substrate of the trench are simultaneously oxidized to form an ISSG in–situ steam growth (ISSG) film. A dielectric layer is deposited that fills the trench and covers the mask layer. The dielectric layer is planarized to expose the silicon nitride layer, then the silicon nitride is stripped.

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